

Title (en)

NICKEL COMPOUND CONTAINING SOLUTION, METHOD FOR PRODUCTION THEREOF, AND METHOD FOR FORMING THIN NICKEL METAL FILM USING THE SAME

Title (de)

LÖSUNGSHALTIGE NICKELVERBINDUNG, HERSTELLUNGSVERFAHREN DAFÜR UND VERFAHREN ZUR BILDUNG EINES DÜNNEN NICKELMETALLFILMS DAMIT

Title (fr)

SOLUTION CONTENANT UN COMPOSÉ DE NICKEL, PROCÉDÉ DE FABRICATION DE CELLE-CI, ET PROCÉDÉ FORMATION D'UN FILM MINCE DE MÉTAL DE NICKEL UTILISANT LADITE SOLUTION

Publication

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Application

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Priority

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Abstract (en)

[origin: EP1770720A1] The present invention provides a nickel compound-containing solution having suitability for screen printing, and a method of forming a nickel metal thin film comprising applying the nickel compound-containing solution by screen printing. In a nickel compound obtained by reacting a reducing compound with nickel salt of organic acid, a nickel compound-containing solution, in which a nickel compound is stable and dissolved in terpeneol, can be provided by using the specific structure compound as the reducing compound. This solution or the solution further containing resin such as cellulose and the like has the viscosity suitable for screening printing. A nickel metal thin film can be formed by applying the nickel compound-containing solution onto a substrate with screen printing and then heat-treating.

IPC 8 full level

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Citation (search report)

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- See references of WO 2005117029A1

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